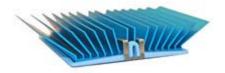
# **BGA Heat Sink - High Performance** maxiFLOW/superGRIP



ATS Part#: ATS-X50450B-C1-R0

Description: 45.00 x 45.00 x 7.50 mm BGA Heat Sink - High Performance maxiFLOW/superGRIP



Heat Sink Type: maxiFLOW
Heat Sink Attachment: superGRIP

Equivalent Part Number: N/A

\*Image above is for illustration purpose only.

#### **Features & Benefits**

- Designed for 45 x 45 mm components
- · Requires minimal space around the component's perimeter; ideal for densely populated PCBs
- Allows the heat sink to be detached and reattached without damaging the component or the PCB, an important feature in the event a PCB may need to be reworked
- Strong, uniform attachment force helps achieve maximum performance from phase-changing TIMs
- Eliminates the need to drill mounting holes in the PCB

#### **Thermal Performance**

AIR VELOCITY		@200 LFM 1.0 M/S	@300 LFM 1.5 M/S	@400 LFM 2.0 M/S	@500 LFM 2.5 M/S	@600 LFM 3.0 M/S	@700 LFM 3.5 M/S	@800 LFM 4.0 M/S
THERMAL RESISTANCE	Unducted Flow	4 °C/W	2.9 °C/W	2.4 °C/W	2.1 °C/W	1.9 °C/W	1.8 °C/W	1.6 °C/W
	Ducted Flow	2.6	N/A	N/A	N/A	N/A	N/A	N/A

### **Product Detail**

Schematic Image	Dimension A	Dimension B	Dimension C	Dimension D	ТІМ	Finish
	45.00 mm	45.00 mm	7.50 mm	61.5 mm	T766	BLUE-ANODIZED
*Image above is for illustration purpose only.	<ul> <li>Dimension</li> <li>Thermal papplication</li> <li>ATS reserperforman</li> <li>ATS certifities</li> </ul>	performance data are n. rves the right to upda nce.	e provided for reference provided for reference ate or change its process assembly is RoHS	m of the base to the nce only. Actual performance only and ducts without notice -6 and REACH complete.	ormance to improv	may vary by



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